

**27~29 July, 2023. Seoul, Korea**

**Application Form**

|  |  |  |  |  |
| --- | --- | --- | --- | --- |
| **\* COUNTRY** | |  | **\* CITY** |  |
| **\* INVENTOR** | | **NAME** | | **SCHOOL / COMPANY NAME** |
| 1. | |  |
| 2. | |  |
| 3. | |  |
| 4. | |  |
| 5. | |  |
| **Write the correct English name and affiliation name / Up to 5 People** | | |
| **Agency**  **(Contact)**  **or Contact Participant** | **Name** |  | | |
| **Tel** |  | | |
| **E-mail** |  | | |
| **Add** |  | | |

**. . 2023**

**Send to here**: E-mail / [Lee37895661@gmail.com](mailto:Lee37895661@gmail.com) / [7935111@naver.com](mailto:7935111@naver.com)

Date : \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

|  |  |
| --- | --- |
| **\*Name of Invention** |  |
| **\*Abstract Of Invention & Photo of Invention** |  |